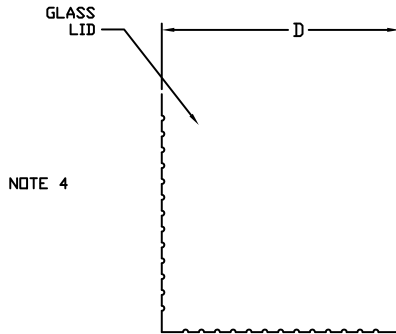
SIDE VIEW

LCC52, 19.05x19.05
CASE 115AP
ISSUE O

DATE 30 JUN 2011



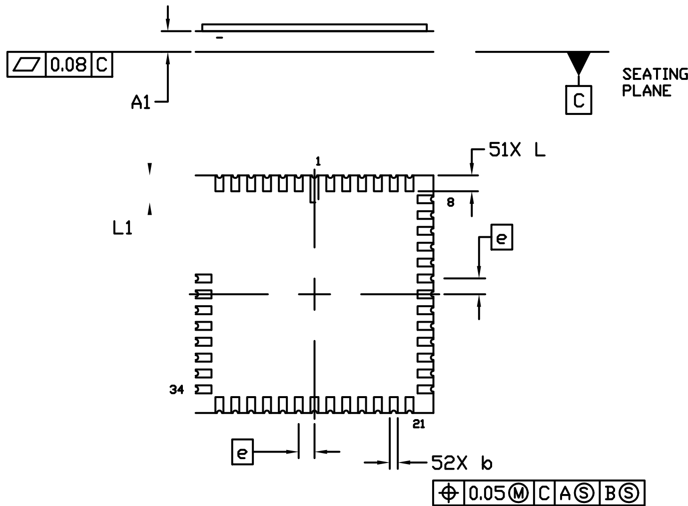
NOTES:
1. DIMENSIONING AND
   Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
   SION A INCLUDES THE PACKA
   LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER
   ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST
   BE LOCATED WITHIN DIMENSIONS D AND E.

BOTTOM VIEW

NOTE 4

NOTE 3

A1	1.65 REF	
b	0.56	0.72
E	18.80	19.43
	18.00 REF	
e	1.27 BSC	
L1	1.96	2.36



GENERIC
MARKING DIAGRAM

PACKAGE
OUTLINE

51X

XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
NNNN = Serial Number

PITCH

52X

1

RECOMMENDED
MOUNTING FOOTPRINT